

Features

- High isolation 3750 V_{RMS}
- OFF-state output terminal voltage: 100 V
- Typical ON-state resistance: 0.6 Ω
- Operating Temperature range 40 °C to 85 °C
- Creepage distance ≥ 5mm
- Distance Through Isolation > 0.4mm
- RoHS and REACH Compliance
- Halogen Free Compliance
- MSL class 1
- Regulatory Approvals
 - ✓ UL UL1577 (E364000)
 - ✓ VDE EN60747-5-5(VDE0884-5)
 - ✓ CQC GB4943.1, GB8898 (14001105803)
 - ✓ IEC62368 (FI/41119)

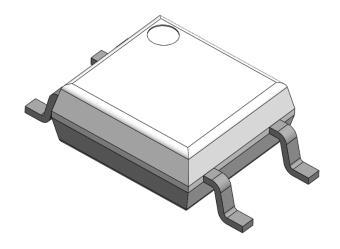
Description

The CTR215-M4 (1-form-A) consists of two MOSFET and one photovoltaic chip optically coupled to an Infrared-emitting diode in 4-lead Mini-Flat package.

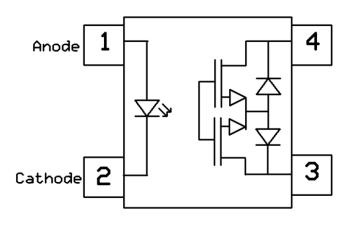
Applications

- Battery Management System (BMS)
- Security Systems
- Smart Meters
- Mechanical relay replacements
- General telecom switching
- Industrial controls
- Automatic measurement equipment

Package Outline



Schematic





Absolute Maximum Ratings $T_A = 25$ °C, unless otherwise specified

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameters	Ratings	Units	Notes
Viso	Isolation voltage (AC, 1 minute, 40 ~ 60% R.H.)	3750	Vrms	
T _{OPR}	Operating temperature	-40 ~ +85	°C	
T _{STG}	Storage temperature	-40 ~ +100	°C	
T _{SOL}	Soldering temperature (For 10 seconds)	260	°C	
Emitter		·		
l _F	Forward current	50	mA	
I _{F(TRANS)}	Peak transient current (≤1µs P.W,300pps)	1	А	
V _R	Reverse voltage	5	V	
Pc	Power dissipation	85	mW	
Tj	Junction Temperature	115	°C	
Detector			·	
Voff	OFF-state output terminal Voltage	100	V	
I _{ON}	ON-state Current	0.5	А	
Po	Output Power dissipation	375 r		
Tj	Junction Temperature	125	°C	
T _{jA}	Junction to Ambient Temperature	60	°C	

Recommended Operating Conditions

Symbol	Parameters	Min	Тур	Max	Units
V _{DD}	Supply Voltage	-	-	80	V
I _{FT}	Trigger LED Current	5	10	20	mA
T _{OPR}	Operating temperature	-40	-	60	$^{\circ}\!\mathbb{C}$



Electrical Characteristics $T_A = 25^{\circ}\text{C}$, unless otherwise specified

Emitter Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward voltage	I _F = 10mA	-	1.4	1.6	V	
I _R	Reverse Current	V _R = 6V	-	-	5	μΑ	
Cin	Input Capacitance	f= 1MHz	-	30	-	pF	

Detector Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
IOFF	OFF-state Current	V _{OFF} =100V	-	-	1	uA	
C _{OFF}	Output Capacitance	V _O = 0V, f=1 MHz	_	30	_	pF	
OOFF	Output Capacitance	VO- 0V, 1-1 WILL	_	30	_	ρı	

Transfer Characteristics

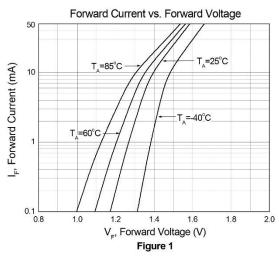
Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
I _{FT}	Trigger LED Current	Ion =Max	-	1.5	3	mA	
Ron	ON-state resistance	I _{ON} =Max, I _F =5 mA , t < 1s	-	0.6	1.5	Ω	

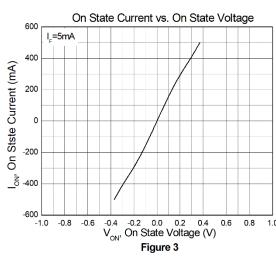
Switching Characteristics

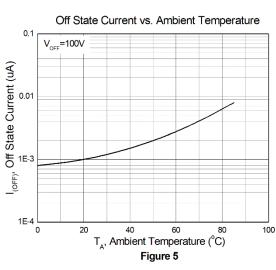
Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
Ton	Turn-on Time	R_L =200 Ω , V_{DD} =20 V , I_F =5 mA	-	1	3	ms	
Toff	Turn-off Time	f=100Hz	-	0.3	2	ms	

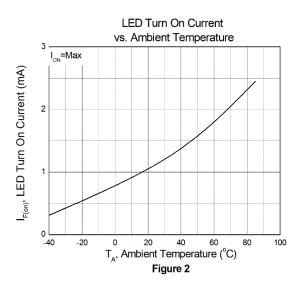


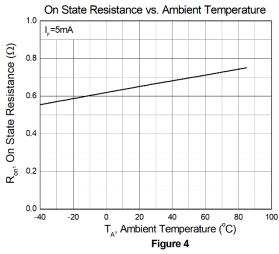
Typical Characteristic Curves T_A = 25°C, unless otherwise specified

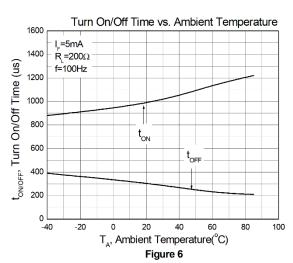






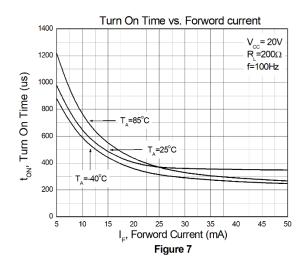


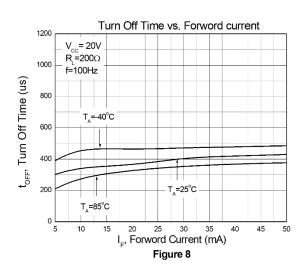




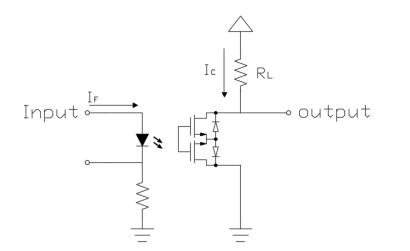


Typical Characteristic Curves $\tau_A = 25$ °C, unless otherwise specified





Test Circuit



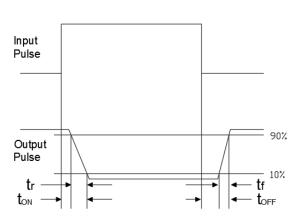
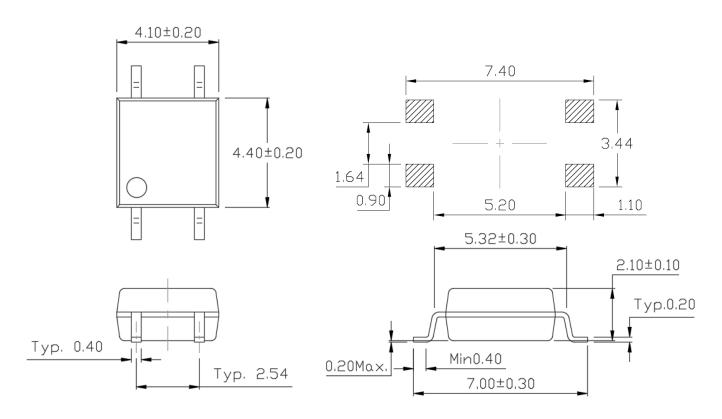


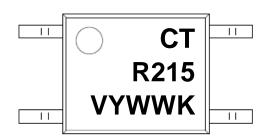
Figure 9: Switching Time Test Circuits



Package Dimension Dimensions in mm unless otherwise stated



Marking Information



Note:

CT : Denotes "CT Micro"

R215: Part Number

X : Option (Blank, A or B)

V : VDE Safety Mark Option (Blank or V)

Y : One Digit Year CodeWW : Two Digit Work WeekK : Manufacturing Code



Ordering Information

CTR215(V)(Z)-M4

CT = Denotes "CT Micro"

R215 = Part Number

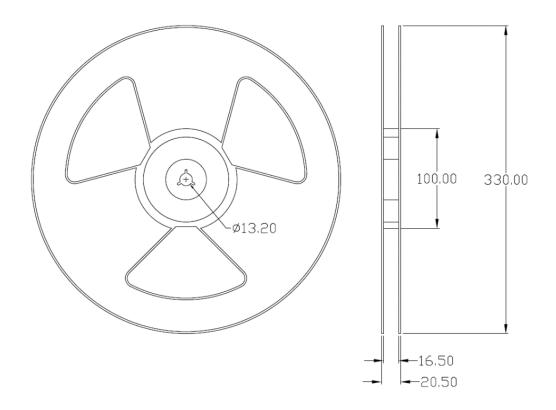
V = VDE Safety Mark Option (Blank or V)

Z = Tape and Reel Option (T1 or T2)

M4 = MFP Package

Option	Option Description	
T1	Surface Mount Lead Forming – With Option 1 Tapping	3000 Units/Reel
T2	Surface Mount Lead Forming – With Option 2 Tapping	3000 Units/Reel

Reel Dimension All dimensions are in mm, unless otherwise stated Option T1/T2

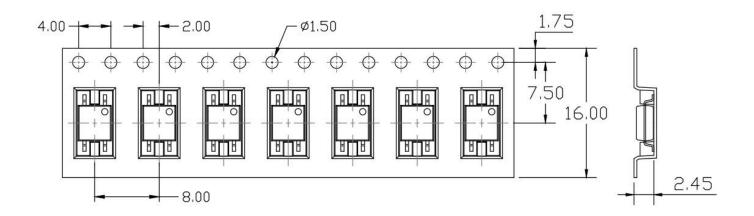




Carrier Tape Specifications Dimensions in mm unless otherwise stated

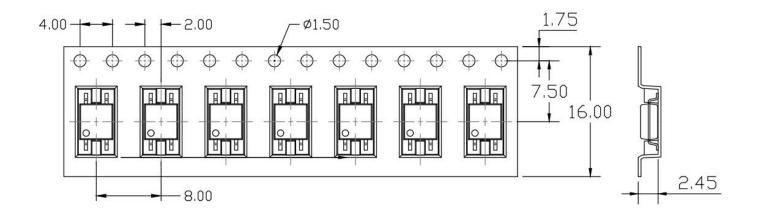
Option T1

Input Direction



Option T2

Input Direction





Solderability spec (Follow the JEDEC standard JESD22-B102)

Reflow Soldering: Immersed surface, other than the end of pin as cut-surface, must be covered by solder.

Solder-Bath: More than 95% of the electrode must be covered with solder.

Wave soldering (Follow the JEDEC standard JESD22-A111)

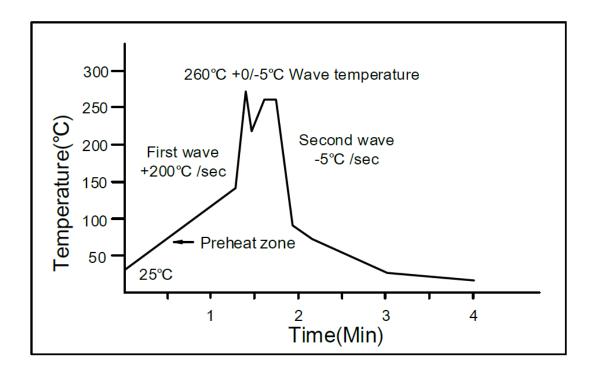
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C.

Time: 10 sec.

Preheat temperature: 25 to 140°C.

Preheat time: 30 to 80 sec.



Iron soldering (Follow the standard MIL-STD 202G, Method 210F)

Allow single lead soldering in every single process.

One time soldering is recommended. Temperature: 350±10°C

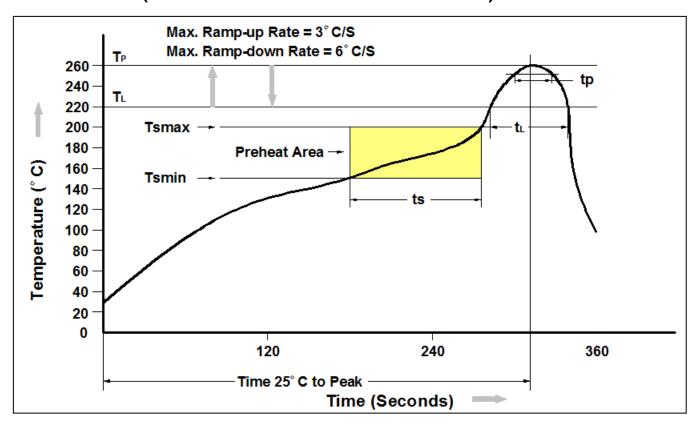
Time: 5 sec max.



4-Pin Mini-Flat DMC-Isolator®

Opto MOS Relays

Reflow Profile (Follow the JEDEC standard J-STD-020)



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t∟ to t⊳)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



CTR215-M4

4-Pin Mini-Flat DMC-Isolator® Opto MOS Relays

DISCLAIMER

DMC-Isolator® IS A TRADEMARK OF CT MICRO INTERNATIONAL CORPORATION AND/OR ITS SUBSIDIARIES. CT MICRO OWNS THE RIGHTS TO A NUMBER OF PATENTS, TRADEMARKS, COPYRIGHTS AND OTHER INTELLECTUAL PROPERTY.

CT MICRO RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. CT MICRO DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN;

DISCOLORATION MIGHT OCCUR ON THE PACKAGE SURFACE AFTER SOLDERING, REFLOW OR LONG TERM USE. THIS DOES NOT IMPACT THE PRODUCT PERFORMANCE NOR THE PRODUCT RELIABILITY.

NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

CT MICRO ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT EXPRESS WRITTEN APPROVAL OF CT MICRO INTERNATIONAL CORPORATION.

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instruction for use provided in the labelling, can be reasonably expected to result in significant injury to the user.
- A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.